



EXPEDITED PROCEDURE – EXAMINING GROUP 2827

09/893588

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Takashi Kumamoto	Examiner:	Alonzo Chambliss
Serial No.:	09/893588	Group Art Unit:	2827
Filed:	June 29, 2001	Docket No.:	884.A98US1
Title:	MULTI-PURPOSE PLANARAZING/BACK-GRIND/PRE-UNDERFULL ARRANGEMENTS FOR BUMPED WAFERS AND DIE		
Assignee:	Intel Corporation	Customer No.:	21186

AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116

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Commissioner for Patents
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In response to the final Office Action mailed August 1, 2003, please amend the application as follows: